

Abstract

Process designed to prevent deposition of contaminating particles on the surface of a micro-component, micro-component storage device and thin layer deposition device

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A process designed to prevent deposition of polarized contaminating particles on the surface of a micro-component consists, according to the invention, in sputtering a beam of particles between the contamination source and the micro-component. At least a part of the particles of the beam has an opposite polarity from that of the contaminating particles. The beam of particles is preferably a plasma and is designed to drag the contaminating particles away from the free surface of the micro-component to a collecting element. The invention also relates to a micro-component storage device and a thin layer deposition device respectively implementing such a process.

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